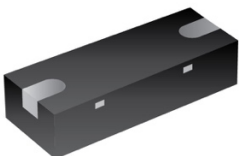


# MATERIAL DECLARATION SHEET



Material Number	CDDFN2-T5.0LC			
Product Line	Semiconductor Products			
Compliance Date	2/1/2018			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.05	Silicon	7440-21-3	100.00%	4.51	4.51
2	Lead Frame	Copper Alloy (NiPdAu)	0.4388	Copper	7440-50-8	95.31%	37.714	39.57
				Nickel	7440-02-0	2.97%	1.175	
				Silicon	7440-21-3	0.64%	0.253	
				Magnesium	7439-95-4	0.15%	0.059	
				Nickel	7440-02-0	0.85%	0.336	
				Palladium	7440-57-3	0.06%	0.024	
3	Epoxy	Polymer	0.05	Aluminum oxide, fibrous	1344-28-1	55.5%	2.503	4.51
				Epoxy resin	Proprietary	16.7%	0.753	
				Epoxy resin	Proprietary	16.7%	0.753	
				Epoxy resin	Proprietary	5.5%	0.248	
				Dapsone	80-08-0	2.2%	0.099	
				Guanidine derivative	Proprietary	2.2%	0.099	

# MATERIAL DECLARATION SHEET



				Silicone Resin	Proprietary	0.6%	0.027	
				Substituted silane	Proprietary	0.6%	0.027	
4	Wire	Noble metal	0.01	Gold	7440-57-5	99.99%	0.90%	0.90
				Misc not to declare	/	0.01%	0.00%	
5	Mold Compound	Polymer	0.56	Silica (Amorphous) A	60676-86-0	80.00%	40.48	50.6
				Silica (Amorphous) B	7631-86-9	13.70%	6.93	
				Epoxy Resin	Trade Secret	3.00%	1.52	
				Phenol Resin	Trade Secret	3.00%	1.52	
				Carbon Black	1333-86-4	0.30%	0.15	
		Total weight	<b>1.1088 mg</b>					

**This Document was updated on: 2/25/2022**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.